

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	"594561".apn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:10
S2	11417	257/667,737,738,778,779,780,782,783.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:17
S3	649	257/667.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:17
S4	2	S3 and (solder adj resist) same underfill	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:18
S5	3	S3 and (solder adj resist) and underfill	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:18

S6	649	257/667.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:26
S7	301	S6 and (bump or ball or solder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:26
S8	8135	((flip adj chip) or (bump or ball or solder)) same underfill	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:38
S9	288	S8 and (solder adj resist) same underfill	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:39
S10	85	S9 and @ad<"20040928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:42
S11	12	("20010050441"   "20030222342"   "5218234"   "5710071"   "6281450"   "6681982").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 16:52
S12	66	S8 and (solder adj resist) same (surround\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 17:09

S13	23	S12 and @ad<"20040928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2009/09/27 17:10
S14	272	tanida-kazumasa\$.in. or miyata-osamu\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 14:00
S15	40512	rohms\$.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 14:00
S16	40667	S14 or S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 14:00
S17	4676212	semiconductor or chip or die or wafer or (integrated adj circuit) or (electronic adj (device or component))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 14:01
S18	1342245	(flip\$3 adj chip) or ball or bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 14:02
S19	315858	S17 and S18	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 14:04

S20	1195	S16 and S19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 14:04
S21	22	("20010050441"   "20030222342"   "20040108594"   "20040235287"   "20050067715"   "20080150159"   "5218234"   "5710071"   "6281450"   "6459144"   "6681982").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 16:12
S22	122	(board or pcb or pwb) same underfill same (solder adj resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/26 16:46
S23	34	(board or pcb or pwb) and underfill and (solder adj resist) and socket	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 11:57
S24	265	(board or pcb or pwb) and (solder adj resist) and socket	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:00
S25	2901	361/633,651,721,737,792.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:13
S26	2148	S25 and @pd< "20040928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:13

S27	297	S26 and (ball or bump or bga)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:13
S28	14	S27 and (solder adj resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:14
S29	42	S26 and (solder adj resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:14
S30	2226	361/716,721,729,792.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:29
S31	1718	S30 and @pd<"20040928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:29
S32	10	S31 and (electrode near end)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:30
S33	313	361/721.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:31

S34	3911	257/686.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:43
S35	1610	S34 and @pd< "20040928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:43
S36	1039	S35 and (pcb or pwb or board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:43
S37	16	S35 and ((pcb or pwb or board) near electrode)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:44
S38	718	S36 and (ball or bump or bga)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:45
S39	44	S38 and (solder adj resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 12:45
S40	49	S36 and (solder adj resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:25

S41	5950	stack\$3 near (board or pcb or pwb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:32
S42	8301	(pcb or pwb or board) near electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:33
S43	83	S41 and S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:33
S44	3624	S41 and @pd<"20040928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:35
S45	75	S44 and (solder adj (resist or mask))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:36
S46	329	S42 and (solder adj (resist or mask))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:38
S47	508	361/790.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/05/30 13:40

S48	3914	257/686.cds.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/06/01 12:08
S49	1610	S48 and @pd<"20040928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/06/01 12:08
S50	1039	S49 and (pcb or pwb or board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	AND	ON	2010/06/01 12:08
S51	25	("4755417"   "4812792"   "4926242").PN. OR ("5248853").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2010/06/01 12:27

6/2/2010 1:58:55 PM

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